

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	821	702/117.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/21 11:20
L2	123	1 and temperature and (integrat\$2 or IC) and test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/21 11:20
S1	176	702/132.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:52
S2	75	702/131.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:45
S3	633	702/130.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:45
S4	433	702/64.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:46
S5	116993	temperature and (integrat\$2 or IC) and test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/21 11:20
S6	24	S1 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:51
S7	5	S2 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:50
S8	93	S3 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:50
S9	49	S4 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:50



S10	4023	temperature same (integrat\$2 or IC) same test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:50
S11	8	S1 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:52
S12	0	S2 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:52
S13	18	S3 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:51
S14	4	S4 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:51
S15	166	S10 and "702"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:58
S16	2	"20040183588"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:00
S17	1	"20050088137"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 11:59
S18	431	327/545.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:00
S19	0	S18 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:01
S20	402	318/806.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:01



S21	8	S18 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:01
S22	12	S20 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:08
S23	21091	((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:46
S24	4104	S23 and ((environmental or ambient) near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:47
S25	688	S24 and (voltage near3 bias\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:17
S26	78	S25 and (thermal near4 resistance)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:16
S27	495	S25 and ((power or voltage) near4 supply)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:19
S28	241	S25 and ((power or voltage) near4 supply with temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:20
S29	228	S28 and (current with voltage)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 12:20
S30	37	702/129.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:44
S31	1	S30 and (temperature and (integrat\$2 or IC) and test)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:46



S32	4207	324/765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:46
S33	821	S32 and (temperature and (integrat\$2 or IC) and test)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:46
S34	192	S32 and (((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:46
S35	36	S34 and ((environmental or ambient) near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:47
S36	21091	((voltage or power or current) with control\$4) and (((semiconductor with substrate) or (integrated adj circuit\$1) or wafer\$1 or chip\$1) with temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:48
S37	4104	S36 and ((environmental or ambient) near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:48
S38	688	S37 and (voltage near3 bias\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/10 15:32
S39	241	S38 and ((power or voltage) near4 supply with temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:48
S40	228	S39 and (current with voltage)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/05/24 13:48
S41	39	S40 and (junction near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/10 15:31
S42	14662	(junction near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 15:31



S43	1864	body near5 voltage near5 bias\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/10 15:36
S44	18	S42 and S43	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/10 15:32
S45	75	body near5 voltage near5 bias\$3 with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/11/10 16:06
S46	78	body near5 voltage near5 bias\$3 with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 15:36
S47	83	body near5 voltage near5 bias\$3 with (temperature or thermal)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 15:37
S48	136	body near5 voltage near5 bias\$3 same (temperature or thermal)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 16:07
S49	38	body near5 voltage near5 bias\$3 same (regulat\$3 or desired or optimaliz\$3 or stabliz\$3 or control\$4 or maintain\$3 or management or optimum) near5 (temperature or thermal)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 15:54
S50	6	S49 and junction with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/10 16:04
S51	2	"6100751".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/11 09:52